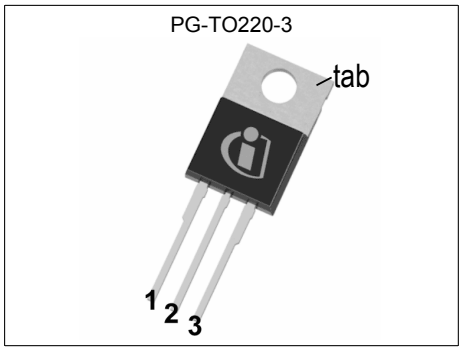
MOSFET

StrongIRFET™ 2 Power-Transistor



Features

- Optimized for a wide range of applications
- N-Channel, normal level
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product validation

Qualified according to JEDEC Standard

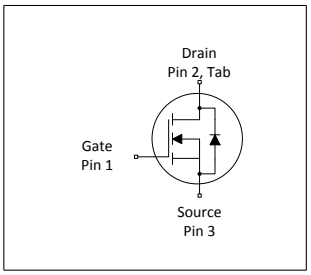


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on),max}$	12.9	mΩ
I_D	52	A
Q_{oss}	26	nC
Q_G	19	nC

Type / Ordering Code	Package	Marking	Related Links
IPP129N10NF2S	PG-TO220-3	129N10NS	-

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1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D	- - - -	- - - -	52 37 33 12	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=6 V, T_C=100 °C V_{GS}=10 V, T_A=25 °C, R_{thJA}=40°C/W[2]
Pulsed drain current[3]	$I_{D,pulse}$	-	-	208	A	T_A=25 °C
Avalanche energy, single pulse[4]	E_{AS}	-	-	31	mJ	I_D=25 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	- -	- -	71 3.8	W	T_C=25 °C T_A=25 °C, R_{thJA}=40 °C/W[2]
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	2.1	°C/W	-
Thermal resistance, junction - ambient, 6 cm² cooling area[2]	R_{thJA}	-	-	40	°C/W	-
Thermal resistance, junction - ambient, minimal footprint	R_{thJA}	-	-	62	°C/W	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.
[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.
[3] See Diagram 3 for more detailed information
[4] See Diagram 13 for more detailed information

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3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.2	3	3.8	V	V_{DS}=V_{GS}, I_D=30 µA
Zero gate voltage drain current	I_{DSS}	- -	0.1 10	1 100	µA	V_{DS}=100 V, V_{GS}=0 V, T_j=25 °C V_{DS}=100 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance[1]	$R_{DS(on)}$	- -	11.6 14.2	12.9 16.2	mΩ	V_{GS}=10 V, I_D=30 A V_{GS}=6 V, I_D=15 A
Gate resistance	R_G	-	0.9	-	Ω	-
Transconductance[2]	g_{fs}	24	-	-	S	|V_{DS}|≥2|I_D|$R_{DS(on)max}$, I_D=30 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	1300	-	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Output capacitance	C_{oss}	-	210	-	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Reverse transfer capacitance	C_{rss}	-	10	-	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	8.8	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r	-	15	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$=1.6 Ω
Turn-off delay time	$t_{d(off)}$	-	13	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$=1.6 Ω
Fall time	t_f	-	3.6	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=30 A, $R_{G,ext}$=1.6 Ω

Table 6 Gate charge characteristics[3]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	6.4	-	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	3.9	-	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Gate to drain charge	Q_{gd}	-	4.1	-	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Switching charge	Q_{sw}	-	6.5	-	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Gate charge total[2]	Q_g	-	19	28	nC	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	4.9	-	V	V_{DD}=50 V, I_D=30 A, V_{GS}=0 to 10 V
Output charge	Q_{oss}	-	26	-	nC	V_{DS}=50 V, V_{GS}=0 V

[1] $R_{DS(on)}$ is specified at a distance of 1.8 mm distance to the package body; mounting at a larger distance increases the overall package resistance of approximately 0.04 mOhm/mm per leg.
[2] Defined by design. Not subject to production test.
[3] See ″Gate charge waveforms″ for parameter definition

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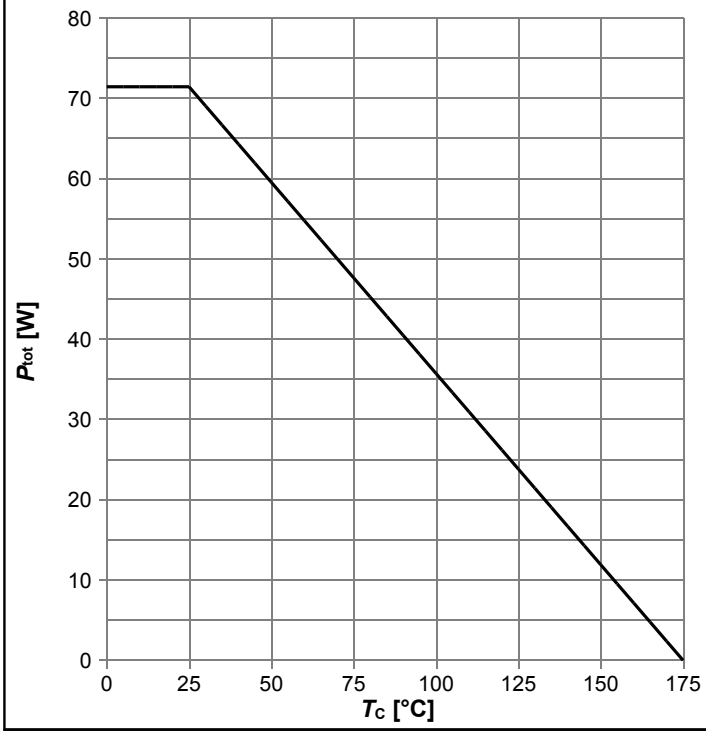
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	51	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	208	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.93	1.2	V	V_{GS}=0 V, I_F=30 A, T_j=25 °C
Reverse recovery time	t_{rr}	-	26	-	ns	V_R=50 V, I_F=30 A, di_F/dt=500 A/µs
Reverse recovery charge	Q_{rr}	-	135	-	nC	V_R=50 V, I_F=30 A, di_F/dt=500 A/µs

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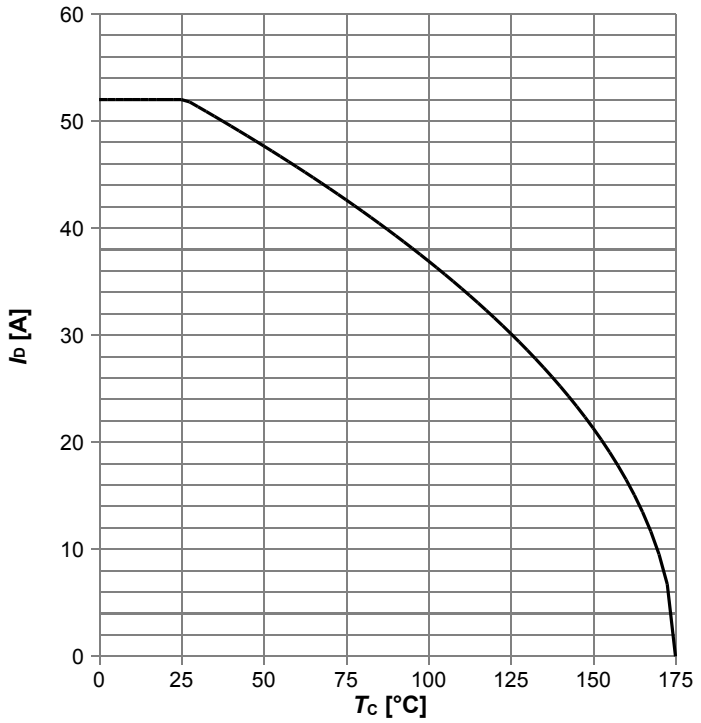
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



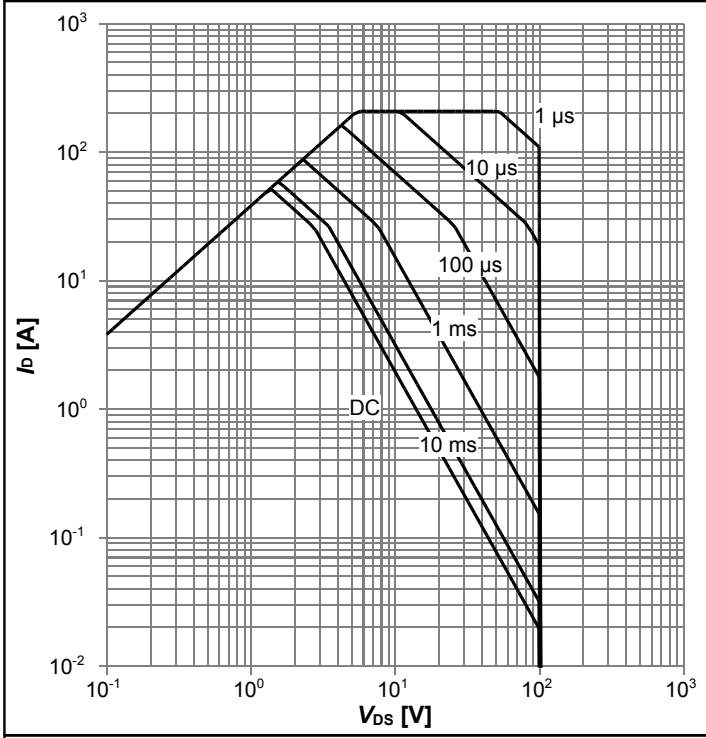
$P_{tot}=f(T_C)$

Diagram 2: Drain current



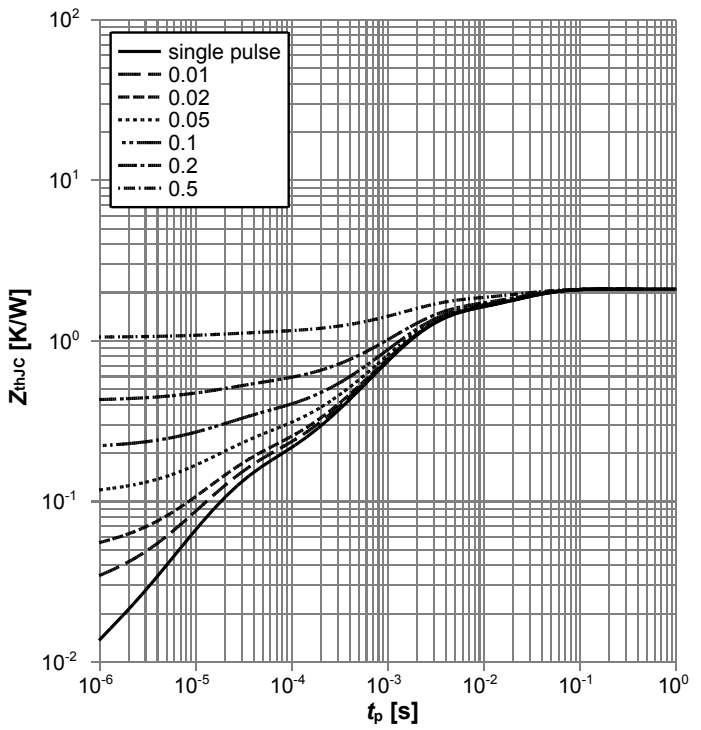
$I_D=f(T_C)$; $V_{GS}\geq 10$ V

Diagram 3: Safe operating area



$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$; parameter: t_p

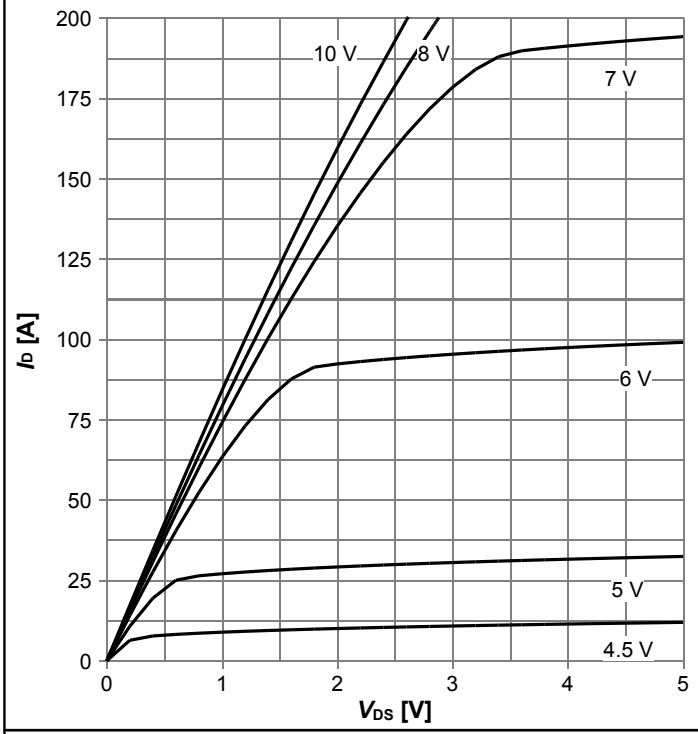
Diagram 4: Max. transient thermal impedance



$Z_{thJC}=f(t_p)$; parameter: $D=t_p/T$

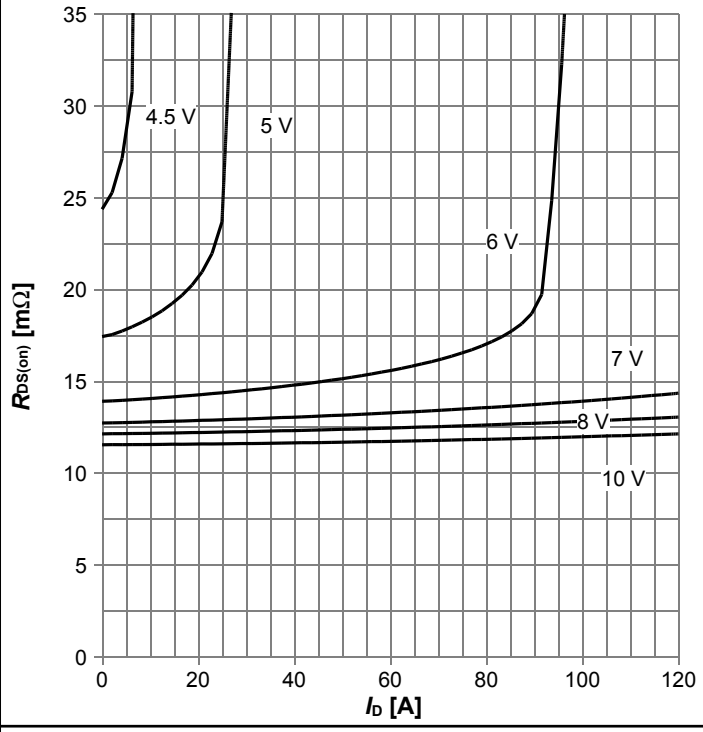
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Diagram 5: Typ. output characteristics



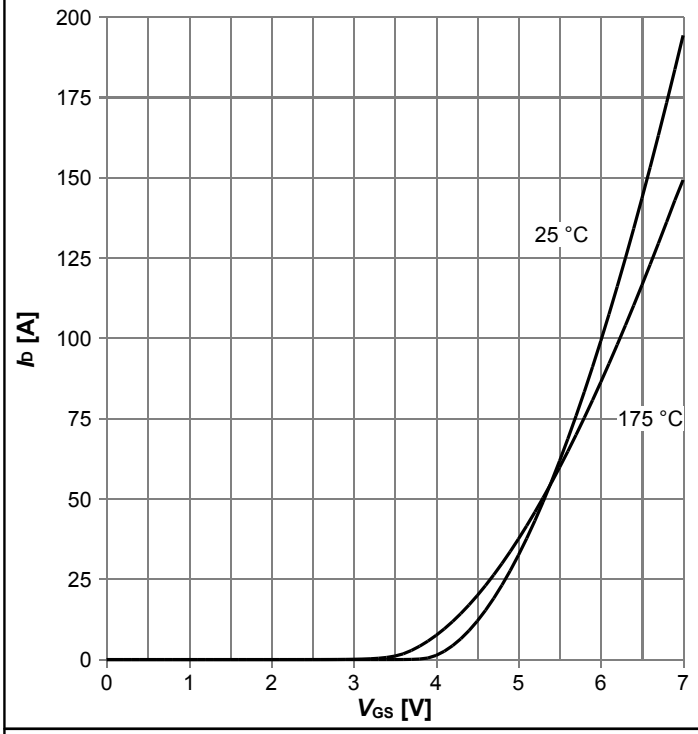
$I_D=f(V_{DS})$, $T_j=25$ °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



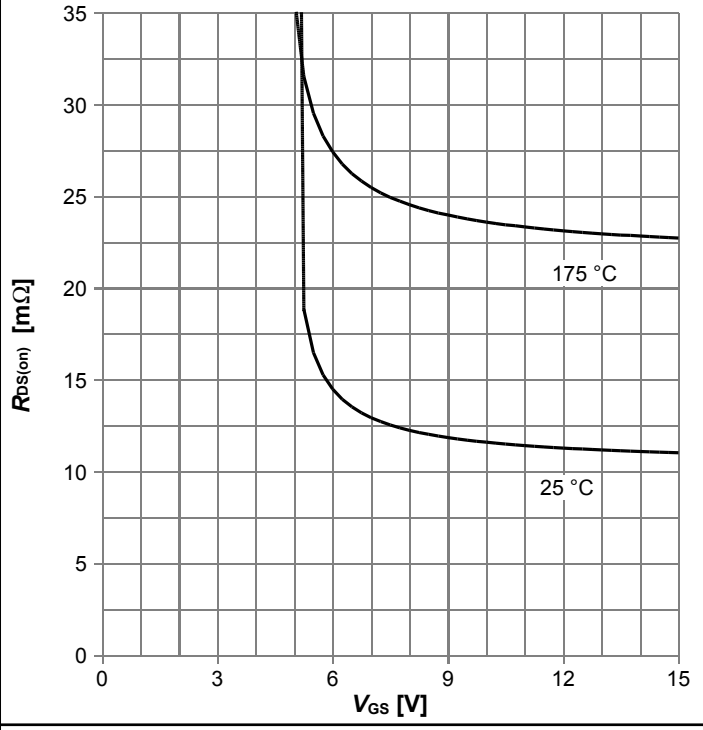
$R_{DS(on)}=f(I_D)$, $T_j=25$ °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



$I_D=f(V_{GS})$, $|V_{DS}|>2|I_D|R_{DS(on)max}$; parameter: T_j

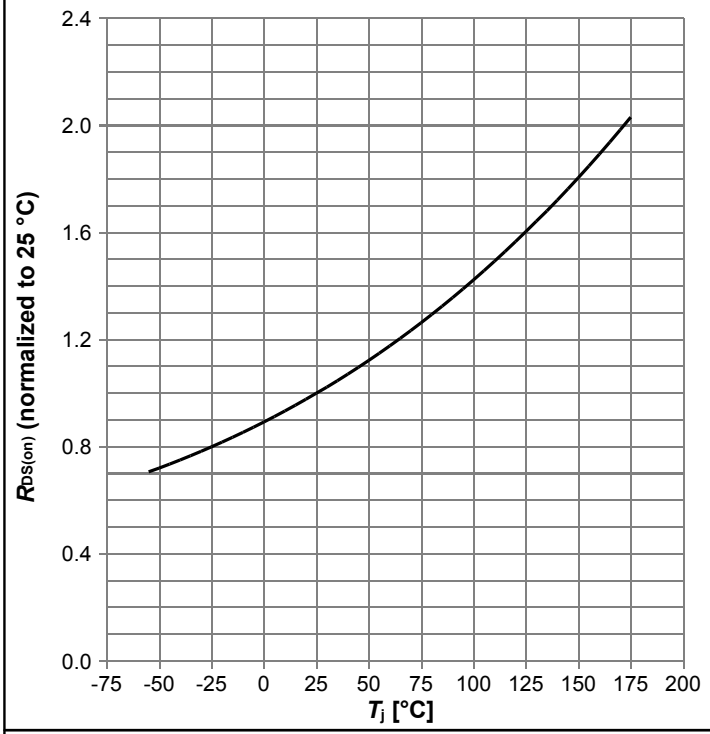
Diagram 8: Typ. drain-source on resistance



$R_{DS(on)}=f(V_{GS})$, $I_D=30$ A; parameter: T_j

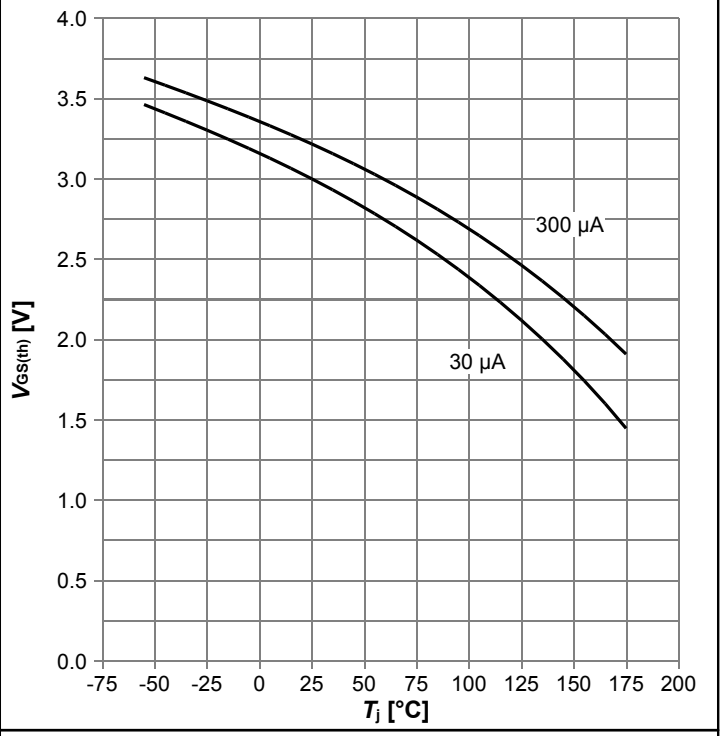
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Diagram 9: Normalized drain-source on resistance



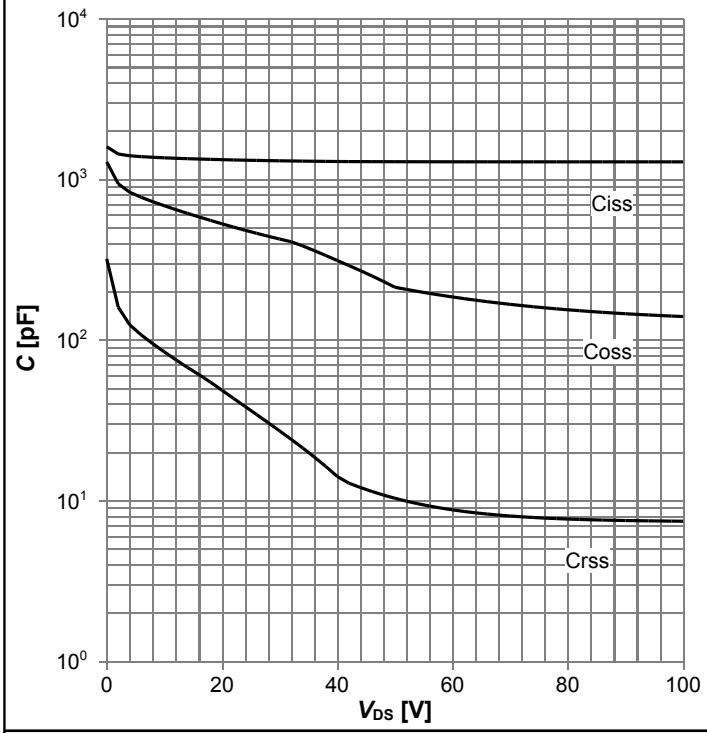
$R_{DS(on)}$=f(T_j), I_D=30 A, V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



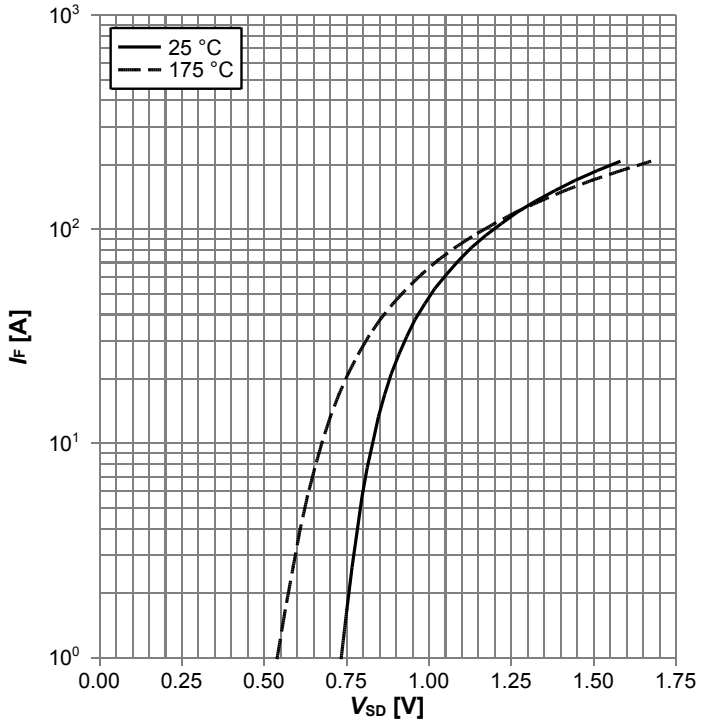
$V_{GS(th}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 11: Typ. capacitances



C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

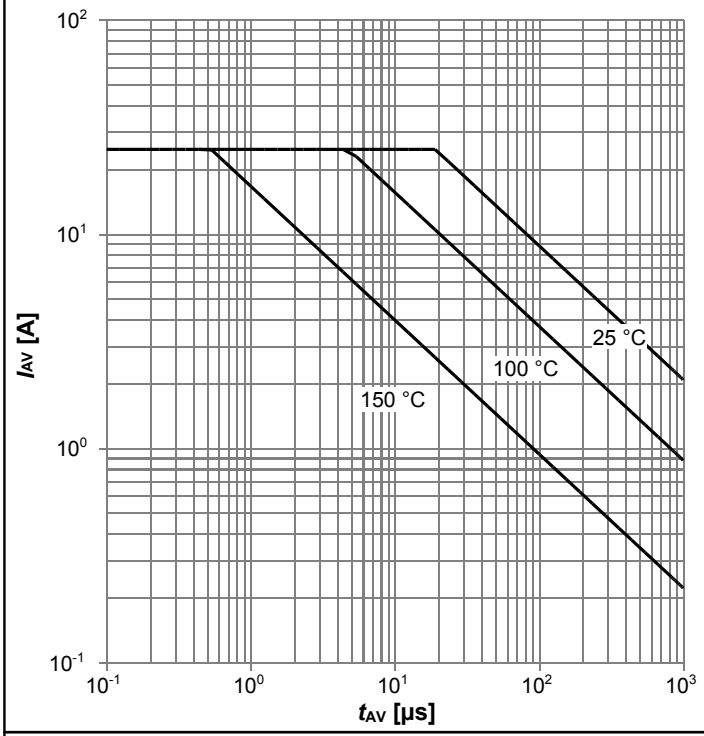
Diagram 12: Typ. forward characteristics of reverse diode



I_F=f(V_{SD}); parameter: T_j

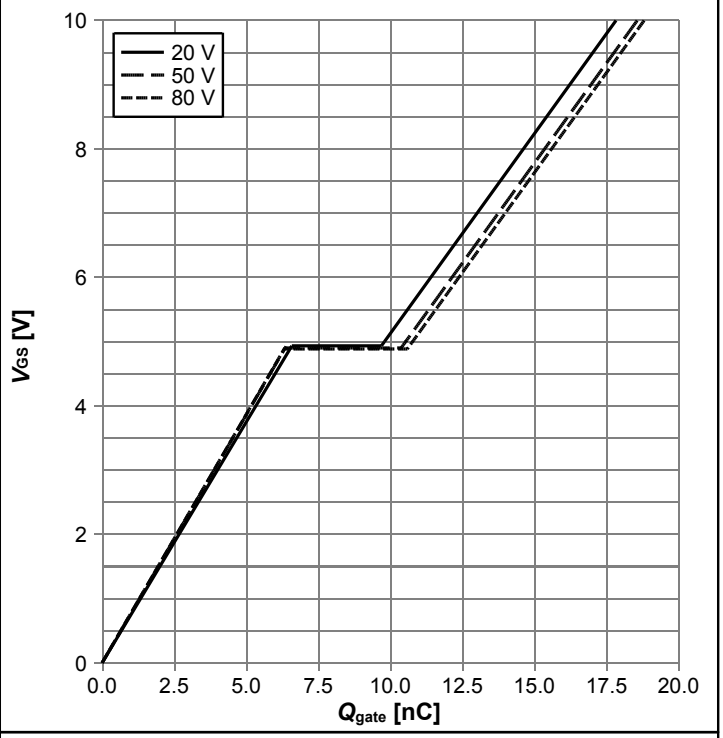
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Diagram 13: Avalanche characteristics



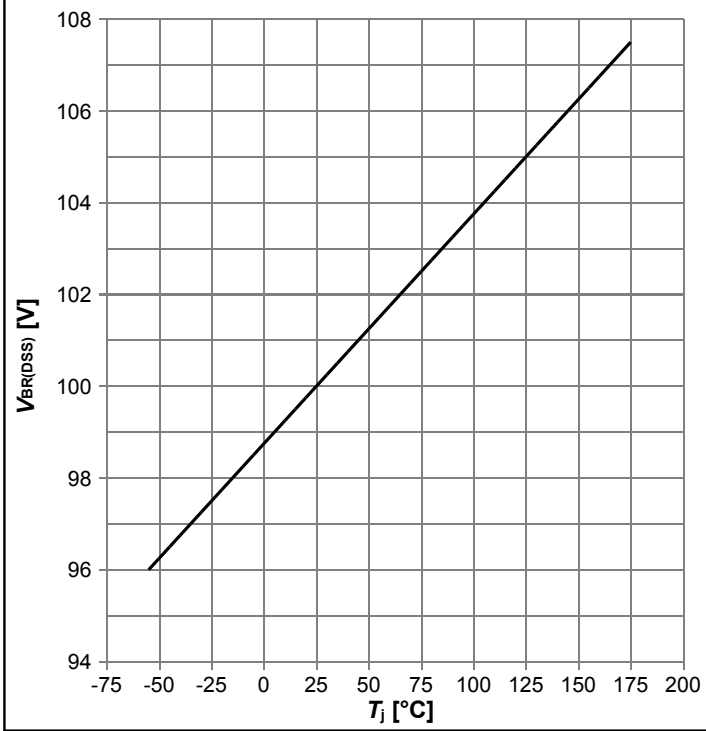
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j,start}$

Diagram 14: Typ. gate charge



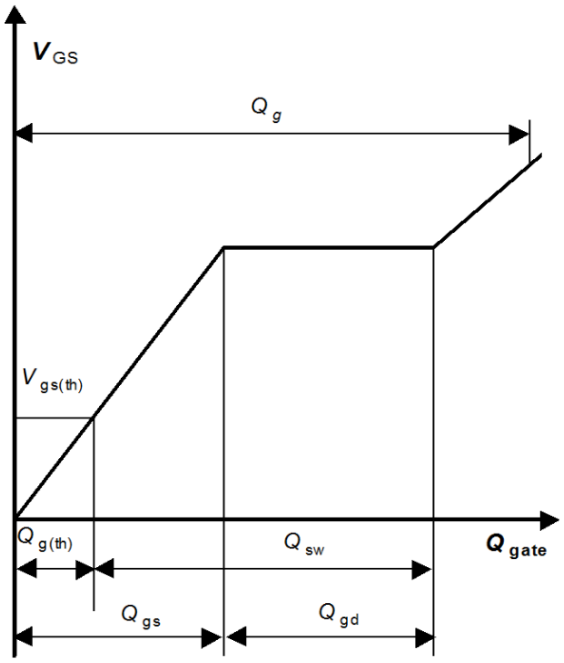
V_{GS}=f(Q_{gate}), I_D=30 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage



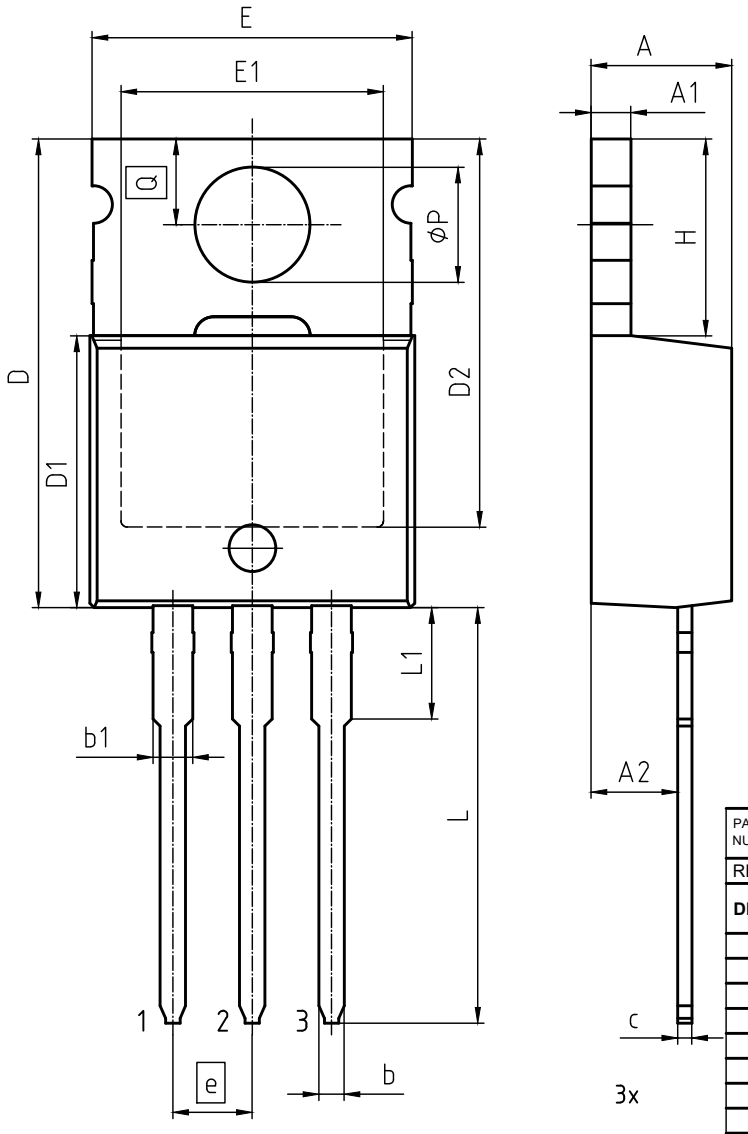
$V_{BR(DSS)}$=f(T_j); I_D=1 mA

Diagram Gate charge waveforms



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5 Package Outlines



PACKAGE - GROUP NUMBER:	PG-TO220-3-U05	
REVISION: 02	DATE: 15.12.2020	
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	4.25	4.75
A1	1.14	1.40
A2	2.47	2.92
b	0.71	0.97
b1	1.14	1.78
c	0.36	0.61
D	14.32	15.80
D1	8.39	9.20
D2	11.89	12.80
E	9.90	10.67
E1	8.10	8.74
e	2.54	
N	3	
H	6.00	6.70
L	13.00	14.40
L1	3.56	4.06
øP	3.54	3.90
Q	2.54	2.94

NOTES:
DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS
GATE BURRS ARE LESS THAN 0.5 mm

Figure 1 Outline PG-TO220-3, dimensions in mm

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Revision History

IPP129N10NF2S

Revision: 2022-06-15, Rev. 2.1

Previous Revision		
Revision	Date	Subjects (major changes since last revision)
2.0	2020-12-18	Release of final version
2.1	2022-06-15	Skip condition "Operating and storage tempt.", update trr and Qrr, footnotes, Diagram 12 and Avalanche energy.

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